ABSTRACT

"Forming an electrical contact on an electronic component."

A method of constructing an electrical contact on an electronic component comprises first forming a protruding electrically conducting stud at a contact location by wire bonding a metal wire to a contact pad of the component. The stud is then contacted with solder, without using a mask, so that a solder bump is deposited on and adheres to the metal stud to form a composite solder contact which is able to form with a contact of another component a solder joint which has good electrical and mechanical properties and which may be reliable fabricated at high density by a low cost method. An electronic component provided with such solder contacts and an electronics component package including such a component are also disclosed.

Fig. 5